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APPLICATION NO.	FILIN	G DATE	FIRST NAMED INVENTOR	ATTORNEY DOCKET NO.	CONFIRMATION NO.
10/624,332	07/22/2003		David R. Hembree	3592.8US (97-0321.08/US)	6977
24247	7590	06/25/2004		EXAMINER	
TRASK BRITT				ROMAN, ANGEL	
P.O. BOX 2550 SALT LAKE CITY, UT 84110		84110		ART UNIT	PAPER NUMBER
				2812	
				DATE MAILED: 06/25/2004	

Please find below and/or attached an Office communication concerning this application or proceeding.

	Application No.	Applicant(s)				
	10/624,332	HEMBREE, DAVID R.				
Office Action Summary	Examiner	Art Unit				
	Angel Roman	2812				
The MAILING DATE of this communication app Period for Reply	ears on the cover sheet with the c	orrespondence address				
A SHORTENED STATUTORY PERIOD FOR REPLY THE MAILING DATE OF THIS COMMUNICATION.  - Extensions of time may be available under the provisions of 37 CFR 1.13 after SIX (6) MONTHS from the mailing date of this communication.  - If the period for reply specified above is less than thirty (30) days, a reply - If NO period for reply is specified above, the maximum statutory period w - Failure to reply within the set or extended period for reply will, by statute, Any reply received by the Office later than three months after the mailing earned patent term adjustment. See 37 CFR 1.704(b).	66(a). In no event, however, may a reply be time within the statutory minimum of thirty (30) days fill apply and will expire SIX (6) MONTHS from cause the application to become ABANDONE	nely filed s will be considered timely. the mailing date of this communication. D (35 U.S.C. § 133).				
Status						
1) Responsive to communication(s) filed on	_•					
2a) ☐ This action is <b>FINAL</b> . 2b) ☑ This						
3) Since this application is in condition for allowance except for formal matters, prosecution as to the merits is						
closed in accordance with the practice under E	x parte Quayle, 1935 C.D. 11, 45	53 O.G. 213.				
Disposition of Claims						
4) Claim(s) 1-4 is/are pending in the application.						
4a) Of the above claim(s) is/are withdrawn from consideration.						
5) Claim(s) is/are allowed.						
6)⊠ Claim(s) <u>1-4</u> is/are rejected.	☑ Claim(s) <u>1-4</u> is/are rejected.					
7) Claim(s) is/are objected to.						
8) Claim(s) are subject to restriction and/or	r election requirement.					
Application Papers						
9) The specification is objected to by the Examine	r.					
10)⊠ The drawing(s) filed on 17 May 2004 is/are: a)	The drawing(s) filed on <u>17 May 2004</u> is/are: a)⊠ accepted or b)□ objected to by the Examiner.					
Applicant may not request that any objection to the	drawing(s) be held in abeyance. See	e 37 CFR 1.85(a).				
Replacement drawing sheet(s) including the correct						
11)☐ The oath or declaration is objected to by the Ex	aminer. Note the attached Office	Action or form PTO-152.				
Priority under 35 U.S.C. § 119						
12) Acknowledgment is made of a claim for foreign  a) All b) Some * c) None of:  1. Certified copies of the priority documents  2. Certified copies of the priority documents  3. Copies of the certified copies of the priority application from the International Bureau  * See the attached detailed Office action for a list	s have been received. s have been received in Applicati rity documents have been receive u (PCT Rule 17.2(a)).	on No ed in this National Stage				
Attachment(s)	4)	(PTO 413)				
<ol> <li>Notice of References Cited (PTO-892)</li> <li>Notice of Draftsperson's Patent Drawing Review (PTO-948)</li> </ol>	4) Linterview Summary Paper No(s)/Mail Da	ate				
3) Information Disclosure Statement(s) (PTO-1449 or PTO/SB/08) Paper No(s)/Mail Date 07/22/03; 05/26/04.	5)  Notice of Informal F 6)  Other:	Patent Application (PTO-152)				

Art Unit: 2812

#### **DETAILED ACTION**

### Specification

1. The disclosure is objected to because of the following informalities: In page 7, line 4; "overcover" should be replaced with --cover--.

Appropriate correction is required.

## Double Patenting

2. The nonstatutory double patenting rejection is based on a judicially created doctrine grounded in public policy (a policy reflected in the statute) so as to prevent the unjustified or improper timewise extension of the "right to exclude" granted by a patent and to prevent possible harassment by multiple assignees. See *In re Goodman*, 11 F.3d 1046, 29 USPQ2d 2010 (Fed. Cir. 1993); *In re Longi*, 759 F.2d 887, 225 USPQ 645 (Fed. Cir. 1985); *In re Van Ornum*, 686 F.2d 937, 214 USPQ 761 (CCPA 1982); *In re Vogel*, 422 F.2d 438, 164 USPQ 619 (CCPA 1970);and, *In re Thorington*, 418 F.2d 528, 163 USPQ 644 (CCPA 1969).

A timely filed terminal disclaimer in compliance with 37 CFR 1.321(c) may be used to overcome an actual or provisional rejection based on a nonstatutory double patenting ground provided the conflicting application or patent is shown to be commonly owned with this application. See 37 CFR 1.130(b).

Effective January 1, 1994, a registered attorney or agent of record may sign a terminal disclaimer. A terminal disclaimer signed by the assignee must fully comply with 37 CFR 3.73(b).

3. Claims 1-4 are rejected under the judicially created doctrine of obviousness-type double patenting as being unpatentable over claims 1-4 of U.S. Patent No. 6,596,565 B1. Although the conflicting claims are not identical, they are not patentably distinct from each other because Hembree discloses an assembly method for a Chip On Board semiconductor device having a semiconductor die having a heat sink cap abutting a portion of a top surface of a substrate including; placing a compliant adhesive-filled gel

Art Unit: 2812

silicone elastomer including cross-linked silicon between a portion of an upper surface of the semiconductor die and a portion of the lower surface of the heat sink cap; pressing the semiconductor die into the heat sink cap to engage the semiconductor die and the heat sink cap in compliant removable adhesion and for causing the edge of the heat sink cap to abut the substrate; and injecting an encapsulant into the heat sink cap engaging at least interior portions of the heat sink cap, at least portions of the semiconductor die, at least portions of the top surface of the substrate, and at lest portions of the compliant adhesive-filled gel silicone elastomer (see Hembree, claims 1-4).

#### Conclusion

- 4. The prior art made of record and not relied upon is considered pertinent to applicant's disclosure. Pompeo et al., Distefano, Toy et al. and Mitchell disclose methods for attaching heat sinks to semiconductor devices using silicone.
- 5. Any inquiry concerning this communication or earlier communications from the examiner should be directed to Angel Roman whose telephone number is (571) 272-1681. The examiner can normally be reached on Monday-Friday 8:00am-5:00pm.

If attempts to reach the examiner by telephone are unsuccessful, the examiner's supervisor, John Niebling can be reached on (571) 272-1679. The fax phone number for the organization where this application or proceeding is assigned is 703-872-9306.

Art Unit: 2812

Information regarding the status of an application may be obtained from the Patent Application Information Retrieval (PAIR) system. Status information for published applications may be obtained from either Private PAIR or Public PAIR. Status information for unpublished applications is available through Private PAIR only. For more information about the PAIR system, see http://pair-direct.uspto.gov. Should you have questions on access to the Private PAIR system, contact the Electronic Business Center (EBC) at 866-217-9197 (toll-free).

AR

June 23, 2004

John F. Niebling

Supervisory Patent Examiner Technology Center 2800